P5Cx012/02x/40/73/80/144 family

Secure dual interface and contact PKI smart card controller

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136232

Product short data sheet
COMPANY PUBLIC

1. General description

1.1 CMOS14 SmartMX family features overview

The CMOS14 SmartMX family members are a modular set of devices featuring:

- 12 KB to 144 KB EEPROM
- 200 KB user ROM
- 6144 B RAM
- High-performance secure Public Key Infrastructure (PKI) coprocessor (RSA, ECC)
- Secure dual/triple-DES coprocessor
- Secure AES coprocessor
- Memory Management Unit (MMU)
- ISO/IEC 7816 contact interface
- Optional ISO/IEC 14443 A Contactless Interface Unit (CIU)
- Optional S^2C interface for NFC communication link
- 5-metal layer 0.14 μm CMOS technology
- EEPROM with typically 500000 cycles endurance and a minimum of 25 years retention time
- Broad spectrum of delivery types
- Optional certified crypto library modules for RSA, ECC, DES, AES, SHA and PRNG
- Optional MIFARE 1K or MIFARE 4K functionality

1.2 CMOS14 SmartMX family properties

The long-established CMOS14 SmartMX family features a significantly enhanced secure smart card IC architecture. Extended instructions for Java and C code, linear addressing, high speed at low power and a universal memory management unit are among many other improvements added to the classic 80C51 core architecture. The technology transfer step from 5-metal layer 0.18 μm to 5-metal layer 0.14 μm CMOS technology offers more advantages in terms of security features, memory resources, crypto coprocessor calculation speed for RSA and ECC as well as availability of secure hardware support for 2-key and 3-key Digital Encryption Standard (DES) and Advanced Encryption Standard (AES) operations.

The contact interface availability, the optional contactless interface and the optional S^2C interface enable the easy implementation of native or open platform and multi-application operating systems in market segments such as banking, E-passports, ID cards, Health cards, secure access, Java cards, Near Field Communication (NFC) connectable mobile hand sets as well as Trusted Platform Modules (TPM).

1.3 Naming conventions

Table 1. Naming conventions

P5xyzzz	SmartMX platform
x	Type of category: C = PKI controller + Triple-DES coprocessor + AES coprocessor on selected products
y	Interface options: C = contact interface - ISO/IEC 7816 D = dual interface - ISO/IEC 7816 + ISO/IEC 14443 contactless interface N = ISO/IEC 7816 + S^2C interface for NFC
zzz	Amount of non-volatile memory in KB, increasing count for further product options

1.4 Cryptographic hardware coprocessors

1.4.1 FameXE coprocessor

The approved and modular FameXE architecture supports the trend of increasing RSA keys with faster execution speeds as well as Elliptic Curve Cryptography (ECC) based on GF(p) or GF(2^n) at best performance. FameXE supports RSA with an operand length of up to 8-kbit (up to 4-kbit with intermediate storage in RAM only).

The FameXE PKI coprocessor supports 192-bit ECC key length that offers the same level of security as 2048-bit RSA. An ECC GF(2^n) based signature, using a 163-bit key can be executed in less than 30 ms providing a security level comparable to 1024-bit RSA. The operand size for ECC, supported by FameXE, is only limited by the 2.5 KB size of the FXRAM. FameXE is easy to use and the flexible interface provides programmers with the freedom to implement their own cryptography solutions. A secure and CC EAL5+ certified crypto library providing a large range of required functions will be available for all devices in order to support customers in implementing public key-based solutions.

1.4.2 Triple-DES coprocessor

The DES widely used for symmetric encryption is supported by a dedicated, high performance, highly attack-resistant hardware coprocessor. Single DES and triple-DES, based on two or three DES keys, can be executed within less than 40 μs. Relevant standards (ISO/IEC, ANSI, FIPS) and Message Authentication Code (MAC) are fully supported. A secure crypto library element for DES is available.

1.4.3 AES coprocessor

SmartMX is the first smart card microcontroller platform to provide a dedicated high performance 128-bit parallel processing coprocessor to support secure AES. The implementation is based on FIPS197 as standardized by the National Institute for Standards and Technology (NIST), and supports key lengths of 128-bit, 192-bit, and

256-bit with performance levels comparable to DES. AES is the next generation for symmetric data encryption and recommended successor to DES providing a significantly improved security level. A secure crypto library element for AES is available.

1.5 SmartMX interfaces

1.5.1 SmartMX contact interface

Operating in accordance with ISO/IEC 7816, the SmartMX contact interface is supported by a built-in Universal Asynchronous Receiver/Transmitter (UART), which enables data rates of up to 1 Mbit/s allowing for the automatic generation of all typical baud rates and supports transmission protocols T = 0 and T = 1. Up to two additional I/Os are available.

1.5.2 SmartMX contactless interface

The optional contactless interface is fully compatible with ISO/IEC 14443 A as well as NXP Semiconductors field proven MIFARE technology. A dedicated Contactless Interface Unit (CIU) manages and supports communication using data rates up to 848 kbit/s. A true anti-collision method (in accordance with ISO/IEC 14443-3) enables multiple cards to be handled simultaneously.

The optional MIFARE functionality provided in configurations B1 (MIFARE 1K implementation) and B4 (MIFARE 4K implementation) safeguard the interface compatibility with any installed MIFARE infrastructure. The ability to run the MIFARE protocol concurrently with other contactless transmission protocols implemented by the user OS (T=CL or self defined) enables the combination of new services and existing applications based on MIFARE (e.g. ticketing) on a single dual interface controller based smart card.

The MIFARE implementation on the Smart*MX* makes use of the approved true random number generator and thus is not susceptible to attacks based on the predictability of random numbers. This emulation is separated from the rest of the Smart*MX* by a firewall that is part of the Common Criteria evaluation.

A tutorial software library for ISO/IEC 14443-3 and ISO/IEC 14443-4 is available to support NXP Semiconductors customers for easy integration of the contactless technology into current system solutions.

1.5.3 SmartMX S^2C interface

The S^2C interface is intended for use with NXP Semiconductors NFC circuits (e.g. PN511, PN531) in order to configure secure NFC systems, for example in mobile hand sets.

Operated both in Contact mode (ISO/IEC 7816) and in S^2C mode, the user defines the final function of the controller chip with its operating system. This allows the same level of security, functionality and flexibility for the contact interface as well as for the S^2C interface.

The S^2C interface is connected to the internal ISO/IEC 14443 CIU. The CIU handles the demodulation and modulation of the S^2C signals which enables full contactless communication via this interface and the NFC IC. As the S^2C interface is connected to the CIU the power to the P5CN080 and P5CN144 must be supplied via the VDD and VSS pads in order to use the S^2C interface. The S^2C interface does not need any software adaptation compared to normal contactless operation.

When connected to the S^2C interface of a NFC IC the device is compatible with existing MIFARE reader infrastructure, and the optional emulation modes of MIFARE 1 K or MIFARE 4 K enable fast system integration and backward compatibility to MIFARE based cards. The communication on the S^2C interface supports both the ISO/IEC 14443 A part 3 and the ISO/IEC 14443 part 4.

1.6 Security features

SmartMX incorporates a wide range of both inherent and OS-controlled security features as countermeasure against all types of attack. NXP Semiconductors apply their extensive knowledge of chip security, combined with handshaking circuit technology, very dense 5-metal layer 0.14 μm technology, glue logic and active shielding methodology for optimum results in CC EAL5+, EMVCo and other third-party certifications and approvals.

SmartMX Memory Management Unit (MMU), designed to define various memory segments and assign security attributes accordingly, supports a strong firewall concept that keeps different applications separate from each other. Only the System mode has full access privileges to all memory space and on-chip peripherals, in User mode the privileges are limited. User mode restrictions are configurable by software running in System mode.

The SmartMX security features are acknowledged as having outstanding properties by most NXP Semiconductors' customers. The countermeasures against light attacks are regarded as "best-in-class".

1.7 Security evaluation and certificates

Hardware security certification in accordance with CC EAL5+ is attained. Also, third-party approval such as EMVCo (VISA, CAST), ZKA and others, depending on the application requirements, are available.

NXP Semiconductors continues to drive forward third-party security evaluations to provide its customers with the relevant information and documentation needed to execute subsequent composite evaluations of implemented applications.

1.8 Security licensing

In addition to the various intellectual properties regarding attack resistance of the NXP Semiconductors' owned SmartMX family, NXP Semiconductors has obtained a patent license for SPA and DPA countermeasures from Cryptography Research Incorporated (CRI). This license covers both hardware and software countermeasures. It is important to customers that countermeasures within the operation system are covered under this license agreement with CRI. Further details can be obtained on request.

1.9 Optional crypto library

NXP Semiconductors offer an optional crypto library for all family types:

- Various algorithms:
  - AES encryption and decryption using the AES coprocessor
  - DES and triple-DES encryption and decryption using the DES coprocessor
  - RSA encryption and decryption, signature generation and verification for straightforward and CRT keys up to 5024 bits

  - RSA key generation
  - ECC over GF(p) signature generation and verification (ECDSA) and Diffie-Hellman key exchange for keys up to 544 bits
  - ECC over GF(p) key generation
  - ECC over GF(2^n) signature generation and verification (ECDSA) and Diffie-Hellman key exchange for keys up to 571 bits
  - ECC over GF(2^n) key generation
  - SHA-1, SHA-224 and SHA-256 hash algorithm
  - Pseudo-Random Number Generator (PRNG)
- Easy to use API for all algorithms
- Secure operation in contact as well as in the contactless mode
- Latest built-in security features to avoid power (SPA/DPA), timing and fault attacks (DFA)
- Common criteria CC EAL5+ certification available [except ECC over GF(2^n)] in accordance with BSI-PP-0002 protection profile

2. Features and benefits

2.1 Standard family features

- EEPROM: choice of 12 KB, 20 KB, 40 KB, 72 KB, 80 KB or 144 KB
  - Data retention time: 25 years minimum
  - Endurance: 500000 cycles minimum
- ROM: 200 KB
- RAM: 6144 B
  - 256 B IRAM + 3.25 KB standard RAM usable for CPU
  - 2560 B FXRAM usable for FameXE
- Dedicated Secure_MX51 smart card CPU (Memory eXtended/enhanced 80C51)
  - 5-metal-layer 0.14 μm CMOS technology
  - Operating in Contact and Contactless mode (dependent on family type option)
  - Featuring a 24-bit universal memory space, 24-bit program counter
  - Combined universal program and data linear address range up to 16 MB
  - Additional instructions to improve:
    - pointer operations
    - performance
    - code density of both C and Java source code
- ISO/IEC 7816 contact interface
- PKI coprocessor FameXE
- Support of major Public Key Cryptography (PKC) systems such as RSA, Elgamel, DSS, Diffie-Hellman, Guillou-Quisquater, Fiat-Shamir and Elliptic Curves
  - 8192 bits maximum key length for RSA with randomly chosen modulus
  - 4096 bits maximum key length for calculation within RAM
  - 32-bit interface
  - Boolean operations for acceleration of standard, symmetric cipher algorithms

- High speed Triple-DES coprocessor (64-bit parallel processing DES engine)
  - Two or three keys loadable
  - DES3 performance < 40 μs
- High speed AES coprocessor (128-bit parallel processing AES engine)
- Memory Management Unit (MMU)
- Low power and low voltage design using NXP Semiconductors' handshaking technology
- Multiple source vectorized interrupt system with four priority levels
- Watch exception provides software debugging facility
- Multiple source RESET system
- Two 16-bit timers
- Highly reliable EEPROM for both data storage and program execution
- Bytewise EEPROM programming and read access
- Versatile EEPROM programming of 1 B to 64 B at a time or, optionally 1 B to 128 B at a time
- Typical EEPROM page erasing time: 1.7 ms
- Typical EEPROM page programming time: 1.0 ms
- Power-saving Idle mode
- Wake-up from Idle mode by RESET or any activated interrupt
- Power-saving Sleep (power-down) mode or Clockstop mode
- Wake-up from Sleep or Clockstop mode by RESET or external interrupt
- Contact configuration and serial interface in accordance with ISO/IEC 7816: GND, VDD, CLK, RST_N, IO1
- ISO/IEC 7816 UART supporting standard protocols T = 0 and T = 1 as well as high speed personalization up to 1 Mbit/s
- External or internally generated configurable CPU clock
- 1 MHz to 10 MHz operating external clock frequency range
  - Internal CPU clock up to 30 MHz with synchronous operation
  - Internal clocking independent of externally applied frequency
- High speed 16-bit CRC engine in accordance with ITU-T polynomial definition
- Low power Random Number Generator (RNG) in hardware, AIS-31 compliant
- 1.62 V to 5.5 V extended operating voltage range for class C, B and A
- Optional extended Class B operation mode (targeted for battery supplied applications)
- −25 °C to +85 °C ambient temperature
- Broad spectrum of delivery types:
  - Wafers
  - Modules

2.2 Product specific family features

- P5CC021, P5CC040, P5CC073, P5CC080 and P5CC144
  - ISO/IEC 7816 contact interface
  - Two additional I/O ports: IO2 and IO3 for full-duplex serial data communication
- P5CD012, P5CD020, P5CD040, P5CD080 and P5CD144
  - CIU fully compatible with ISO/IEC 14443A:
    - 13.56 MHz operating frequency

- fully supports the T = CL protocol in accordance with ISO/IEC 14443-4
- supported data transfer rates: 106 kbit/s, 212 kbit/s, 424 kbit/s and 848 kbit/s
- MIFARE reader infrastructure compatibility via optional MIFARE 1 K or 4 K emulation including built-in anticollision support

  - Two additional I/O ports: IO2 and IO3 for full-duplex serial data communication
- P5CN080 and P5CN144
  - S^2C interface
  - One additional I/O port: IO2 for full-duplex serial data communication

2.3 Security features

- Enhanced security sensors:
  - Low and high clock frequency sensor
  - Low and high temperature sensor
  - Low and high supply voltage sensor
  - Single Fault Injection (SFI) attack detection
  - Light sensors (included integrated memory light sensor functionality)
- Electronic fuses for safeguarded mode control
- Active shielding
- Unique ID for each die
- Clock input filter for protection against spikes
- Power-up and power-down reset
- Optional programmable card disable feature
- Memory security (encryption and physical measures) for RAM, EEPROM and ROM
- Memory Management Unit (MMU) including memory protection:
  - Secure multi-application operating systems via two different operation modes: System mode and User mode
  - OS-controlled access restriction mechanism to peripherals in User mode
  - Memory mapping up to 8 MB code memory
  - Memory mapping up to 8 MB (64-kbit) data memory
- Optional disabling of ROM read instructions by code executed in EEPROM
- Optional disabling of any code execution out of RAM
- EEPROM programming:
  - No external clock
  - Hardware sequencer controlled
  - On-chip high voltage generation
  - Enhanced error correction mechanism
- 64 B or 128 B EEPROM for customer-defined security FabKey, featuring batch-, wafer- or die-individual security data, included encrypted diversification features on request
- 14 B user write-protected security area in EEPROM (byte access, inhibit functionality per byte)
- 32 B write-once security area in EEPROM (bit access)
- 32 B user read-only area in EEPROM (byte access)
- Customer-specific EEPROM initialization available

2.4 Design-in support

- Approved development tool chain:
  - Keil PK51 development tool package including μVision3/dScope C51 simulator, additional specific hardware drivers including simulation of contactless interface and ISO/IEC 7816 card interface board. A SmartMX DBox allows software debugging and integration tests.
  - Ashling Ultra-Emulator platform, stand-alone ROM prototyping boards and ISO/IEC 7816 and ISO/IEC 14443 card interface board. Code coverage and performance measurement software tools for real-time software testing.
  - Dual interface dummy modules OM6711 (PDM 1.1 - SOT658) with special antenna bonding on C4 and C8 for testing the implanting process and antenna connection.
- Tutorial C source libraries for:
  - contactless communication in accordance with ISO/IEC 14443, Part 3 and 4
  - T = 1 communication in accordance with ISO/IEC 7816, Part 3
  - EEPROM Read/Write routines

3. Applications

3.1 Application areas

- Banking
- Java cards
- E-passports
- ID cards
- Secure access
- Trusted platform modules

4. Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DD}	supply voltage	Class A: 5 V range		4.5	5.0	5.5	V
		Class B: 3 V range		2.7	3.0	3.3	V
		Class BE: 3 V range	[1]	2.2	3.0	3.3	V
		Class C: 1.8 V range		1.62	1.8	1.98	V
EEPROM characteristics							
t_{ret}	retention time (EEPROM data)	T_{amb} = +55 °C		25	-	-	years
$N_{endu(W)}$	write endurance	under all operating conditions		5×10^5	-	-	cycles

[1] In extended Class B (Class BE) operation mode (targeted for battery powered applications), Class C is not supported.

5. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
P5CC021UA	FFC	8 inch wafer (sawn; 150 μm thickness; on film frame carrier; electronic fail die marking according to SECSII format)	not applicable
P5CC040UA			
P5CC073UA			
P5CC080UA			
P5CC144UA			
P5CD012UA			
P5CD020UA			
P5CD040UA			
P5CD080UA			
P5CD144UA			
P5CN080UA			
P5CN144UA			
P5CD012UE	FFC	8 inch wafer (sawn; 75 μm thickness; on film frame carrier; electronic fail die marking according to SECSII format)	not applicable
P5CD020UE			
P5CD040UE			
P5CD080UE			
P5CD144UE			
P5CC021TS	SSOP20	plastic shrink small outline package; 20 leads; body width 4.4 mm	SOT266-1
P5CC040TS			
P5CC073TS			
P5CC080TS			
P5CC144TS			

Table 3. Ordering information *…continued*

Type number	Package		
	Name	Description	Version
P5CC021HN	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 × 5 × 0.85 mm	SOT617-1
P5CC040HN			
P5CC073HN			
P5CC080HN			
P5CC144HN			
P5CN080HN			
P5CN144HN			
P5CD012A4	MOB4	contactless chip card module (super 35 mm tape format, module thickness 320 μm)	SOT500-2
P5CD020A4			
P5CD040A4			
P5CD080A4			
P5CD144A4			
P5CD012A6	MOB6	contactless chip card module (super 35 mm tape format, module thickness 250 μm)	SOT500-3
P5CD020A6			
P5CD040A6			
P5CD080A6			
P5CD144A6			
P5CC021XS	PCM1.1	contact chip card module (super 35 mm tape format, 8-contact)	SOT658-1
P5CC040XS			
P5CC073XS			
P5CC080XS			
P5CC144XS			
P5CC021XD	Pd-PCM1.1	palladium plated contact chip card module (super 35 mm tape format, 8-contact)	SOT658-1
P5CC040XD			
P5CC080XD			
P5CC144XD			
P5CD012X1	PDM1.1	dual interface chip card module (Plug-in type; super 35 mm tape format, 8-contact)	SOT658-3
P5CD020X1			
P5CD040X1			
P5CD080X1			
P5CD144X1			
P5CD012X0	PDM1.1	dual interface chip card module (super 35 mm tape format, 8-contact)	SOT658-3
P5CD020X0			
P5CD040X0			
P5CD080X0			
P5CD144X0			

Table 3. Ordering information *…continued*

Type number	Package		
	Name	Description	Version
P5CD012XD	Pd-PDM1.1	palladium plated dual interface chip card module (super 35 mm tape format, 8-contact)	SOT658-3
P5CD020XD			
P5CD040XD			
P5CD080XD			
P5CD144XD			
P5CC073XI	P-M8.4-8-1	dual interface chip card module (super 35 mm tape format, 8-contact)	SOT708
P5CD080XI			
P5CD144XI			

Table 4. Feature table

Product type	EEPROM [KB]	User ROM [KB]	Total RAM [KB]	CXRAM [KB]	FXRAM [KB]	Coprocessor			ISO/IEC 7816 IO pads	Interface option
						FameXE	DES	AES		
P5CD012	12	200	6	3.5	2.5	yes	yes	yes	3	dual interface
P5CC021	20	200	6	3.5	2.5	yes	yes	yes	3	contact
P5CD020	20	200	6	3.5	2.5	yes	yes	yes	3	dual interface
P5CC040	40	200	6	3.5	2.5	yes	yes	yes	3	contact
P5CD040	40	200	6	3.5	2.5	yes	yes	yes	3	dual interface
P5CC073	72	200	6	3.5	2.5	yes	yes	yes	3	contact
P5CN080	80	200	6	3.5	2.5	yes	yes	yes	2	contact + S^2C interface for NFC
P5CC080	80	200	6	3.5	2.5	yes	yes	yes	3	contact
P5CD080	80	200	6	3.5	2.5	yes	yes	yes	3	dual interface
P5CN144	144	200	6	3.5	2.5	yes	yes	yes	2	contact + S^2C interface for NFC
P5CC144	144	200	6	3.5	2.5	yes	yes	yes	3	contact
P5CD144	144	200	6	3.5	2.5	yes	yes	yes	3	dual interface

6. Functional diagram

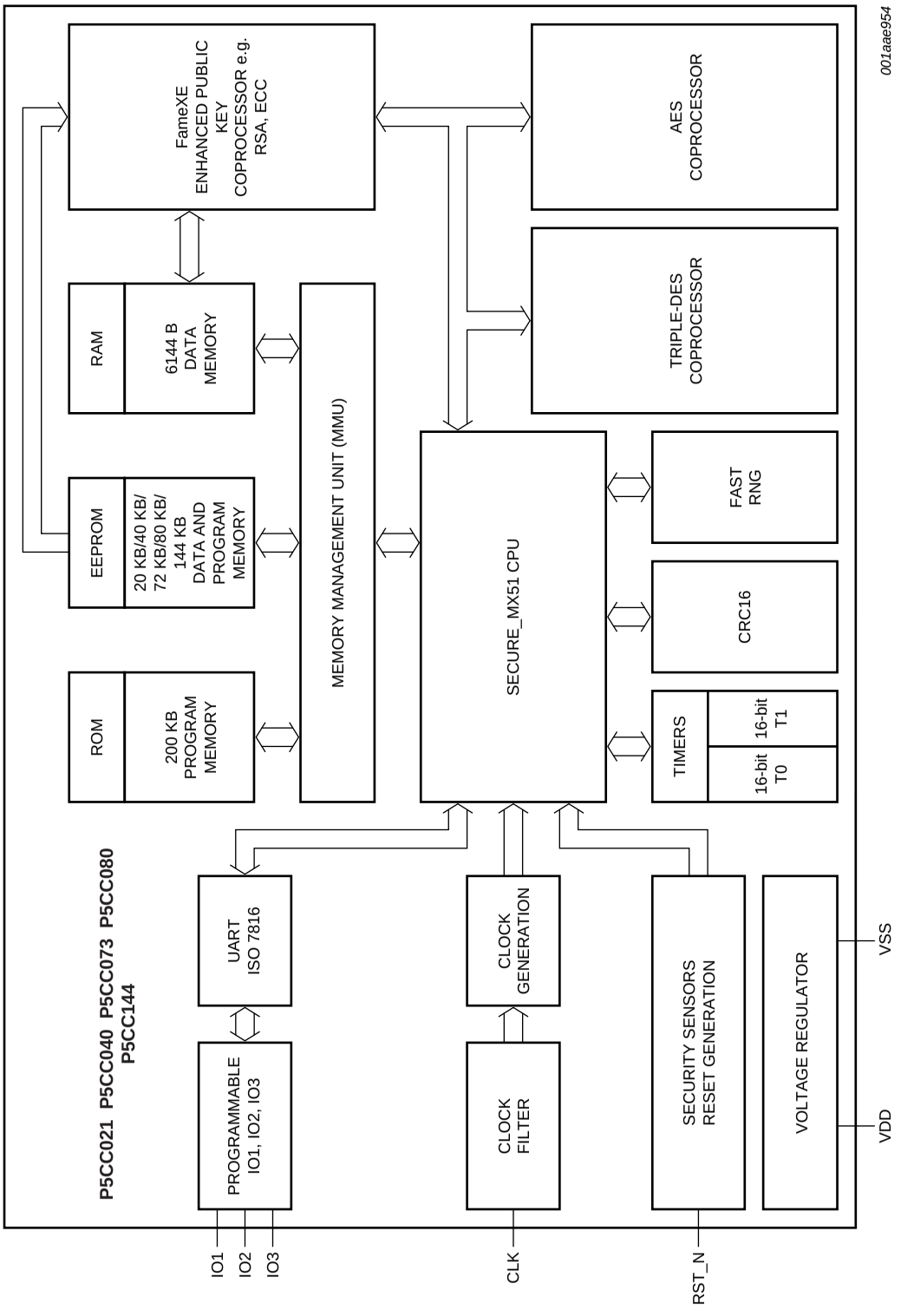

Fig 1. Functional diagram P5CC021/P5CC040/P5CC073/P5CC080/P5CC144

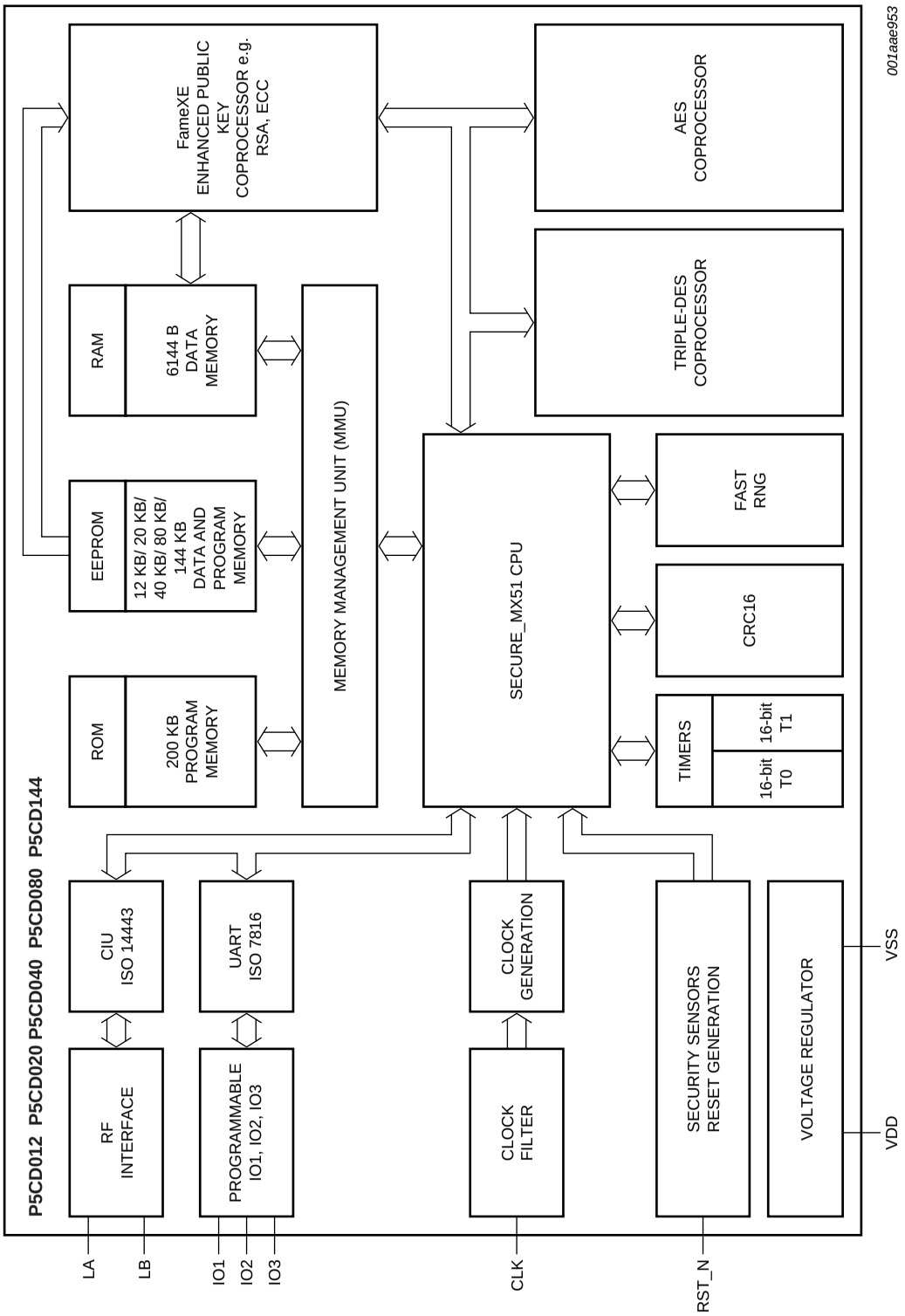

Fig 2. Functional diagram P5CD012/P5CD020/P5CD040/P5CD080/P5CD144

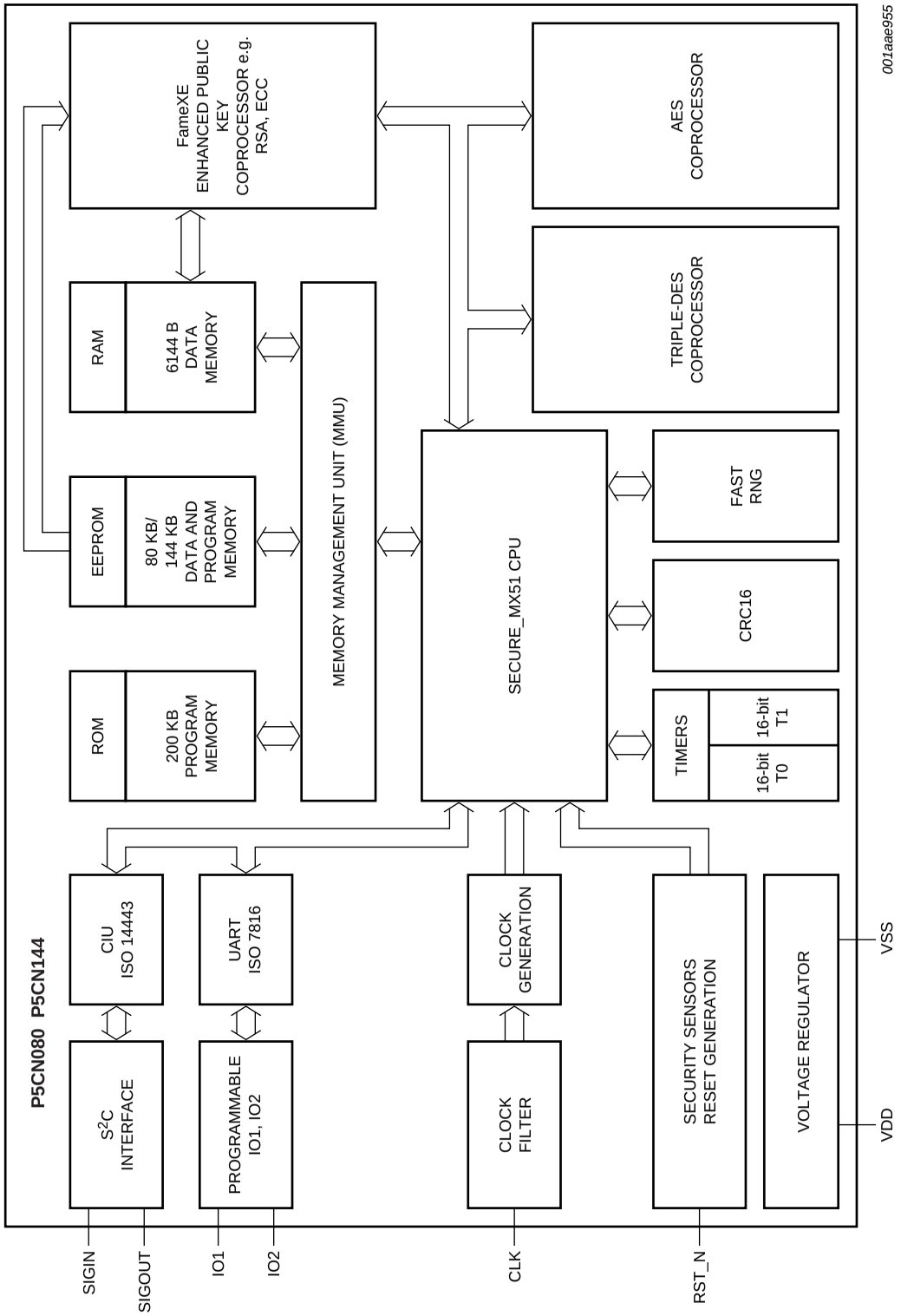

Fig 3. Functional diagram P5CN080/P5CN144

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to V_{SS} (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage			−0.5	+6.0	V
V_I	input voltage	any signal pad		−0.5	V_{DD} + 0.5	V
I_I	input current	pad IO1, IO2 or IO3		-	±15.0	mA
I_O	output current	pad IO1, IO2 or IO3		-	±15.0	mA
I_{lu}	latch-up current	V_I < 0 V or V_I > V_{DD}		-	±100	mA
V_{ESD}	electrostatic discharge voltage	pads VDD, VSS, CLK, RST_N, IO1, IO2, IO3	[1]	-	±4.0	kV
		pads LA, LB	[1]	-	±2.0	kV
P_{tot}	total power dissipation		[2]	-	1	W
T_{stg}	storage temperature		[3]	-	-	°C

[1] MIL Standard 883-D method 3015; human body model; C = 100 pF, R = 1.5 kΩ; T_{amb} = −25 °C to +85 °C.

[2] Depending on appropriate thermal resistance of the package.

[3] Depending on delivery type, refer to *NXP Semiconductors General Specification for 8 ” Wafers* and to *NXP Semiconductors Contact & Dual Interface Chip Card Module Specification*.

8. Abbreviations

Table 6. Abbreviations

Acronym	Description
AES	Advanced Encryption Standard
AIS	Automatic Identification System
API	Application Programming Interface
ASK	Amplitude Shift Keying
CC	Common Criteria
CIU	Contactless Interface Unit
CRC	Cyclic Redundancy Check
CRT	Chinese Remainder Theorem
DES	Digital Encryption Standard
DFA	Differential Fault Analysis
DPA	Differential Power Analysis
DSS	Digital Signature Standard
ECC	Elliptic Curve Cryptography
ECDSA	Elliptic Curve Digital Signature Algorithm
EEPROM	Electrically Erasable Programmable Read-Only Memory
FIPS	Federal Information Processing Standard

Table 6. Abbreviations *...continued*

Acronym	Description
ID	IDentifier
I/O	Input/Output
IRAM	Intelligent Random Access Memory
GF	Galois Function
MAC	Message Authentication Code
MMU	Memory Management Unit
NFC	Near Field Communication
OS	Operating System
PKC	Public Key Cryptography
PKI	Public Key Infrastructure
PRNG	Pseudo-Random Number Generator
RNG	Random Number Generator
RSA	Rivest, Shamir and Adleman
S^2C	SigIn-SigOut-Connection
SFI	Single Fault Injection
SHA	Secure Hash Algorithm
SMD	Surface Mounted Device
SPA	Simple Power Analysis
TPM	Trusted Platform Module
UART	Universal Asynchronous Receiver/Transmitter

9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
P5CX012_02X_40_73_80_144_FAM_SDS_3.2	20110829	Product short data sheet		P5CX012_02X_40_73_80_144_FAM_SDS_3.1
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Document version number revised • Section Section 1.5.2: corrected MIFARE emulation to MIFARE implementation • corrected endurance 500 000 typical to 500 000 minimum • added SSOP package in ordering information • added new Trademark • corrected MIFARE emulation to MIFARE implementation • corrected endurance 500 000 typical to 500 000 minimum • added SSOP package in ordering information • added new Trademark			
P5CX012_02X_40_73_80_144_FAM_SDS_3.1	20100615	Product short data sheet	-	P5CX012_02X_40_73_80_144_FAM_SDS_1.2
Modifications:	• Section 1.1: Retention time changed to 25 years and added new bullet item. • Section 1.2: Second paragraph updated. • Section 1.6: Second paragraph updated, added last paragraph. • Section 1.8: New section. • Section 2.1: Retention time changed to 25 years and changed minimum number of cycles to 500000. • Section 2.2: Product features for types P5CD012, P5CD020, P5CD040, P5CD080 and P5CD144 updated. • Section 2.4: Last bullet item updated. • Section 10.5: Trademarks added.			
P5CX012_02X_40_73_80_144_FAM_SDS_1.2	20080124	Objective short data sheet	-	P5CX02X_40_73_80_144_FAM_SDS_1.1
P5CX02X_40_73_80_144_FAM_SDS_1.1	20070424	Objective short data sheet	-	P5CX02X_40_80_144_FAM_SDS_1.0
P5CX02X_40_80_144_FAM_SDS_1.0	20070216	Objective short data sheet	-	-

10. Legal information

10.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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ICs with DPA Countermeasures functionality

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11. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

12. Tables

13. Figures

14. Contents

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